

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	13	((die wafer substrate) and (chamfer bevel\$3) and edge and (groove recess mesa) and (dic\$3 saw\$3 cut\$4 etch\$3) and (separat\$3 singulat\$3 divid\$3 detach\$3)).clm.	US-PGPU B	OR	ON	2007/03/05 00:04
L5	16	((die wafer substrate) and (chamfer bevel\$3) and edge and (groove recess mesa) and (dic\$3 saw\$3 cut\$4 etch\$3) and (separat\$3 singulat\$3 divid\$3 detach\$3)).clm.	US-PGPU B	OR	ON	2007/03/05 00:04